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(54) **PRINTED CIRCUIT BOARD**

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(57) **ABSTRACT**

A printed circuit board includes a printed wiring board including an insulative substrate having a first surface and a second surface opposite to the first surface, and wiring provided on the second surface of the insulative substrate to face the through-holes. The insulative substrate has flexibility and through-holes passing through the insulative substrate from the first surface to the second surface. A semiconductor element is mounted on the first surface of the insulative substrate of the printed wiring board and has element terminals interposed between the printed wiring board and the semiconductor element. Conductive members filled in the through-holes connect the element terminals and the wiring. The insulative substrate has elasticity in which an elongation percentage of the insulative substrate is 20% or more. The wiring is formed from a conductive polymer or an elastic conductive paste in which conductive particles are mixed into a resin material.